



Micro Systems Technologies
engineering for life

Semiconductor Technology

- Ceramic and metal packages
- Stacked die packages
- Hermetic packages
- Transfer molding
- A variety of I/O configurations
- Miniaturization solutions

Semiconductor Technology



Download PDF

One of MST's core areas of expertise lies in the development and manufacture of miniaturized, implantable electronic modules.

All mission critical functions are accessible within the group to provide customized solutions. Capabilities for providing miniaturized packages include design, substrate manufacturing, component selection and validation as well as all major semiconductor packaging processes.

DYCONEX AG, an MST company located in Bassersdorf, Switzerland, is an expert and technological leader in high-density interconnects based on flex, rigid-flex and rigid technology.

Micro Systems Engineering GmbH, an MST company located in Berg, Germany, is a leading manufacturer of ceramic substrates and has solid and proven expertise in applying all major semiconductor packaging technologies including transfer molding.

Micro Systems Engineering, Inc, an MST company located in Lake Oswego, USA, is a leading specialist in medical microelectronics for Class III applications. Its expertise in the development of complete packages includes the layout of printed circuit board, miniaturized component definition as well as design verification and extensive reliability tests.

Semiconductor Packaging

MST offers various customized packaging solutions for a wide range of base materials, I/O configurations and housing types.

The newest technology development enables the production of SDBGAs (Stacked Die Ball Grid Arrays) in small and medium-sized volumes applying transfer molding technology, laser marking and singulation.

Base Materials

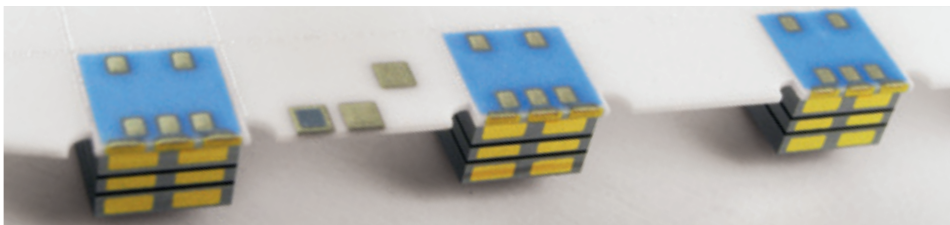
- LTCC
- Al_2O_3
- PCB

I/O-Configurations

- **Ball Grid Array (BGA)**
 - Stacked Die BGA (SDBGA)
 - High voltage BGA
- Land Grid Array (LGA)
- Castellated
- Single In-Line/Dual In-Line (SIL/DIL)
- Quad Flat Packages (QFP)

Housing

- Non-hermetic housings using plastic/metal covers or organic coatings
- Hermetic housings by soldering



MST Showroom

The MST Companies:

DYCONEX AG
LITRONIK Batterietechnologie GmbH
Micro Systems Engineering GmbH
Micro Systems Engineering, Inc.

Micro Systems Technologies Management GmbH
Singapore Branch Office
10 Kallang Avenue #13-10/11/12
Aperia Tower 2, Singapore 339510
Phone +65 9681 3798
info@mst.com
www.mst.com

Micro Systems Technologies, Inc.
6024 SW Jean Road
Lake Oswego, OR 97035, USA
Phone +1(503) 744 8900
Toll free 800 318 7672
sales.msti@mst.com
www.mst.com



Micro Systems Technologies
engineering for life

Micro Systems Technologies
Management GmbH
Sieversufer 7-9
DE-12359 Berlin, Germany
Phone +49 (30) 68905-4001
info@mst.com
www.mst.com